

INA103

Low Noise, Low Distortion INSTRUMENTATION AMPLIFIER

FEATURES

- **LOW NOISE:** $1\text{nV}/\sqrt{\text{Hz}}$
- **LOW THD+N:** 0.0009% at 1kHz, $G = 100$
- **HIGH GBW:** 100MHz at $G = 1000$
- **WIDE SUPPLY RANGE:** $\pm 9\text{V}$ to $\pm 25\text{V}$
- **HIGH CMRR:** $>100\text{dB}$
- **BUILT-IN GAIN SETTING RESISTORS:**
 $G = 1, 100$
- **UPGRADES AD625**

APPLICATIONS

- **HIGH QUALITY MICROPHONE PREAMPS**
(REPLACES TRANSFORMERS)
- **MOVING-COIL PREAMPLIFIERS**
- **DIFFERENTIAL RECEIVERS**
- **AMPLIFICATION OF SIGNALS FROM:**
Strain Gages (Weigh Scale Applications)
Thermocouples
Bridge Transducers

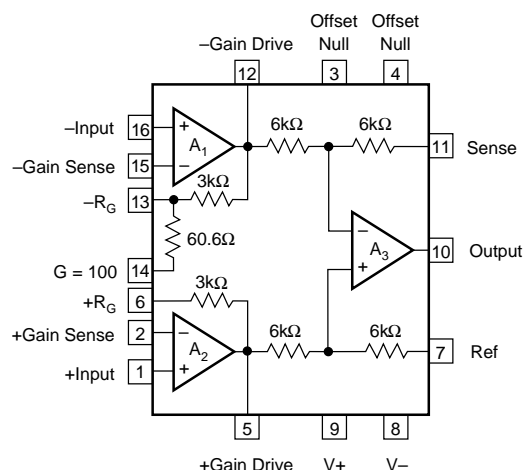
DESCRIPTION

The INA103 is a very low noise, low distortion monolithic instrumentation amplifier. Its current-feedback circuitry achieves very wide bandwidth and excellent dynamic response. It is ideal for low-level audio signals such as balanced low-impedance microphones. The INA103 provides near-theoretical limit noise performance for 200Ω source impedances. Many industrial applications also benefit from its low noise and wide bandwidth.

Unique distortion cancellation circuitry reduces distortion to extremely low levels, even in high gain. Its balanced input, low noise and low distortion provide superior performance compared to transformer-coupled microphone amplifiers used in professional audio equipment.

The INA103's wide supply voltage (± 9 to $\pm 25\text{V}$) and high output current drive allow its use in high-level audio stages as well. A copper lead frame in the plastic DIP assures excellent thermal performance.

The INA103 is available in 16-pin plastic DIP and SOL-16 surface-mount packages. Commercial and Industrial temperature range models are available.



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Internet: <http://www.burr-brown.com/> • FAXLine: (800) 548-6133 (US/Canada Only) • Cable: BBRCORP • Telex: 066-6491 • FAX: (520) 889-1510 • Immediate Product Info: (800) 548-6132

SPECIFICATIONS

All specifications at $T_A = +25^{\circ}\text{C}$, $V_S = \pm 15\text{V}$ and $R_L = 2\text{k}\Omega$, unless otherwise noted.

PARAMETER	CONDITIONS	INA103KP, KU			UNITS
		MIN	TYP	MAX	
GAIN Range of Gain Gain Equation ⁽¹⁾ Gain Error, DC $G = 1$ $G = 100$ Equation Gain Temp. Co. $G = 1$ $G = 100$ Equation Nonlinearity, DC $G = 1$ $G = 100$	$\pm 10\text{V}$ Output $\pm 10\text{V}$ Output $\pm 10\text{V}$ Output	1	$G = 1 + 6\text{k}\Omega/R_G$ 0.005 0.07 0.05 10 25 25 0.0003 0.0006	1000 0.05 0.25 0.01 0.01	V/V V/V % % % ppm/ $^{\circ}\text{C}$ ppm/ $^{\circ}\text{C}$ ppm/ $^{\circ}\text{C}$ % of FS ⁽²⁾ % of FS
OUTPUT Voltage, $R_L = 600\Omega$ $R_L = 600\Omega$ Current Short Circuit Current Capacitive Load Stability	$T_A = T_{\text{MIN}}$ to T_{MAX} $V_S = \pm 25$, $T_A = 25^{\circ}\text{C}$ $T_A = T_{\text{MIN}}$ to T_{MAX}	± 11.5 ± 20 ± 40	± 12 ± 21 ± 70 10	 	V V mA mA nF
INPUT OFFSET VOLTAGE Initial Offset RTI ⁽³⁾ (KU Grade) vs Temp $G = 1$ to 1000 $G = 1000$ vs Supply	$T_A = T_{\text{MIN}}$ to T_{MAX} $T_A = T_{\text{MIN}}$ to T_{MAX} $\pm 9\text{V}$ to $\pm 25\text{V}$		(30 + 1200/G) 1 + 20/G 0.2 + 8/G	(250 + 5000/G) 4 + 60/G	μV μV $\mu\text{V}/^{\circ}\text{C}$ $\mu\text{V}/^{\circ}\text{C}$ $\mu\text{V/V}$
INPUT BIAS CURRENT Initial Bias Current vs Temp Initial Offset Current vs Temp	$T_A = T_{\text{MIN}}$ to T_{MAX} $T_A = T_{\text{MIN}}$ to T_{MAX}		2.5 15 0.04 0.5	12 1	μA nA/ $^{\circ}\text{C}$ μA nA/ $^{\circ}\text{C}$
INPUT IMPEDANCE Differential Mode Common-Mode			60 \parallel 2 60 \parallel 5		M Ω \parallel pF M Ω \parallel pF
INPUT VOLTAGE RANGE Common-Mode Range ⁽⁴⁾ CMR $G = 1$ $G = 100$	 DC to 60Hz DC to 60Hz	± 11 72 100	± 12 86 125		V dB dB
INPUT NOISE Voltage ⁽⁵⁾ 10Hz 100Hz 1kHz Current, 1kHz	$R_S = 0\Omega$		2 1.2 1 2		nV/ $\sqrt{\text{Hz}}$ nV/ $\sqrt{\text{Hz}}$ nV/ $\sqrt{\text{Hz}}$ pA/ $\sqrt{\text{Hz}}$
OUTPUT NOISE Voltage A Weighted, 20Hz-20kHz	1kHz 20Hz-20kHz		65 -100		nV/ $\sqrt{\text{Hz}}$ dBu
DYNAMIC RESPONSE -3dB Bandwidth: $G = 1$ $G = 100$ Full Power Bandwidth $V_{\text{OUT}} = \pm 10\text{V}$, $R_L = 600\Omega$ Slew Rate THD + Noise Settling Time 0.1% $G = 1$ $G = 100$ Settling Time 0.01% $G = 1$ $G = 100$ Overload Recovery ⁽⁶⁾	Small Signal Small Signal $G = 1$ $G = 1$ to 500 $G = 100$, $f = 1\text{kHz}$ $V_O = 20\text{V}$ Step $V_O = 20\text{V}$ Step 50% Overdrive		6 800 240 15 0.0009 1.7 1.5 2 3.5 1		MHz kHz kHz V/ μs % μs μs μs μs μs

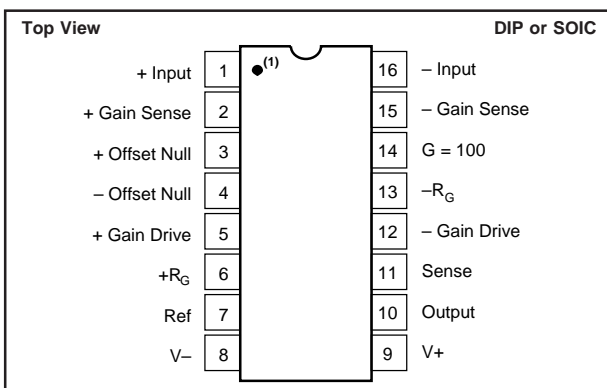
NOTES: (1) Gains other than 1 and 100 can be set by adding an external resistor, R_G between pins 2 and 15. Gain accuracy is a function of R_G . (2) FS = Full Scale. (3) Adjustable to zero. (4) $V_O = 0\text{V}$, see Typical Curves for V_{CM} vs V_O . (5) $V_{\text{NOISE RTI}} = \sqrt{V_{\text{N INPUT}}^2 + (V_{\text{N OUTPUT}}/\text{Gain})^2 + 4\text{KTR}_G}$. See Typical Curves. (6) Time required for output to return from saturation to linear operation following the removal of an input overdrive voltage.

SPECIFICATIONS (CONT)

All specifications at $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$ and $R_L = 2\text{k}\Omega$, unless otherwise noted.

PARAMETER	CONDITIONS	INA103KP, KU			UNITS
		MIN	TYP	MAX	
POWER SUPPLY					
Rated Voltage			±15		V
Voltage Range		±9		±25	V
Quiescent Current			9	12.5	mA
TEMPERATURE RANGE					
Specification		0		+70	°C
Operation		−40		+85	°C
Storage		−40		+100	°C
Thermal Resistance, θJA			100		°C/W

PIN CONFIGURATION



NOTE: (1) Pin 1 Marking—SOL-16 Package

PACKAGE/ORDERING INFORMATION

PRODUCT	PACKAGE	PACKAGE DRAWING NUMBER ⁽¹⁾	TEMPERATURE RANGE
INA103KP	Plastic DIP	180	0°C to +70°C
INA103KU	SOL-16	211	0°C to +70°C

NOTE: (1) For detailed drawing and dimension table, please see end of data sheet, or Appendix C of Burr-Brown IC Data Book.

ELECTROSTATIC DISCHARGE SENSITIVITY

Any integrated circuit can be damaged by ESD. Burr-Brown recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet published specifications.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

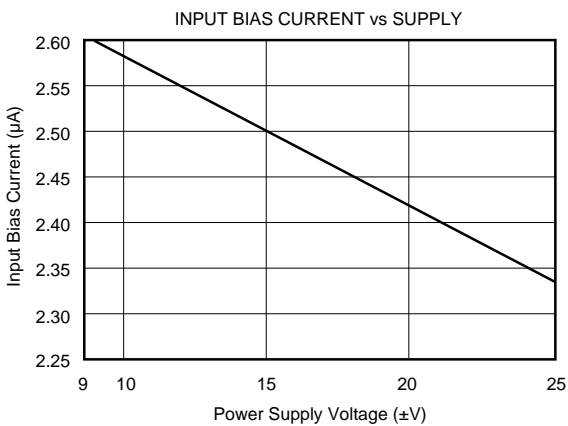
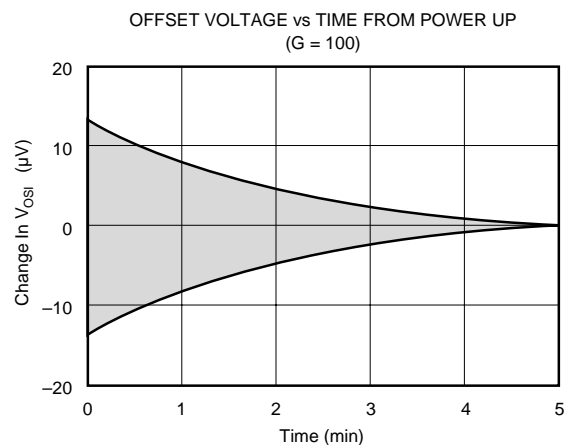
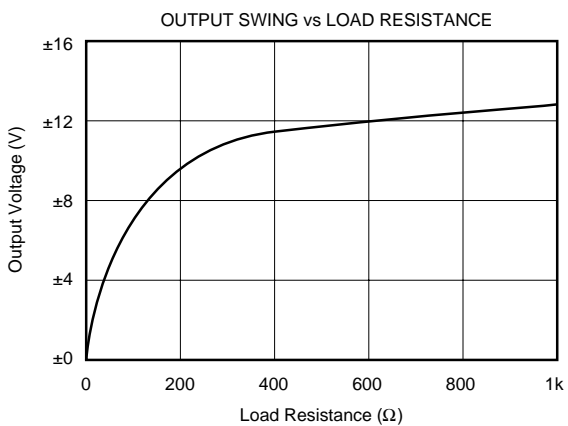
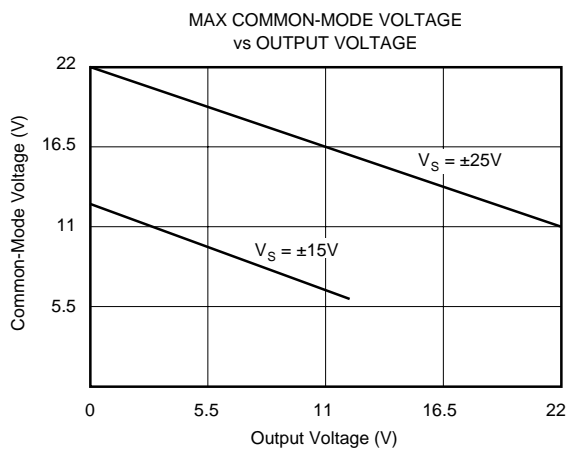
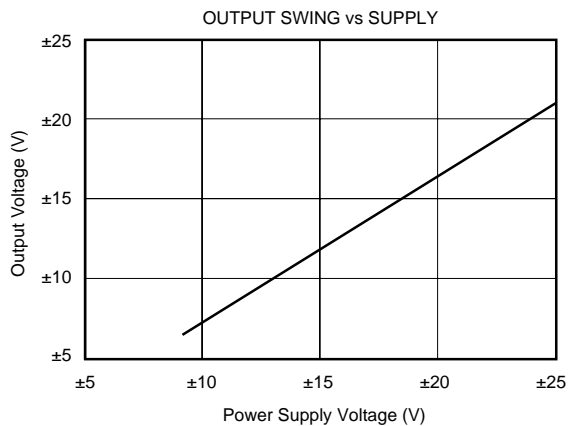
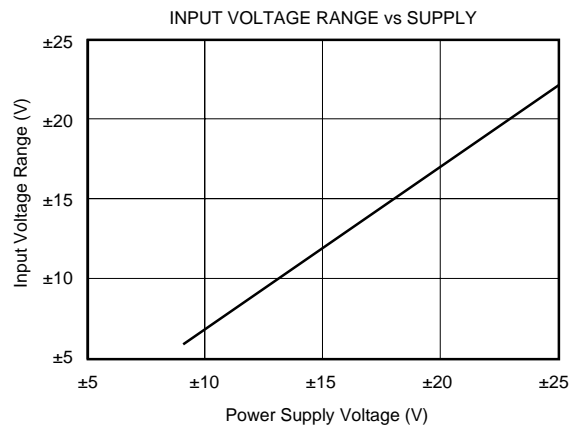
Power Supply Voltage	$\pm 25\text{V}$
Input Voltage Range, Continuous	$\pm V_S$
Operating Temperature Range:	-40°C to +85°C
Storage Temperature Range:	-40°C to +85°C
Junction Temperature:	
P, U Package	+125°C
Lead Temperature (soldering, 10s)	+300°C
Output Short Circuit to Common	Continuous

NOTE: (1) Stresses above these ratings may cause permanent damage.

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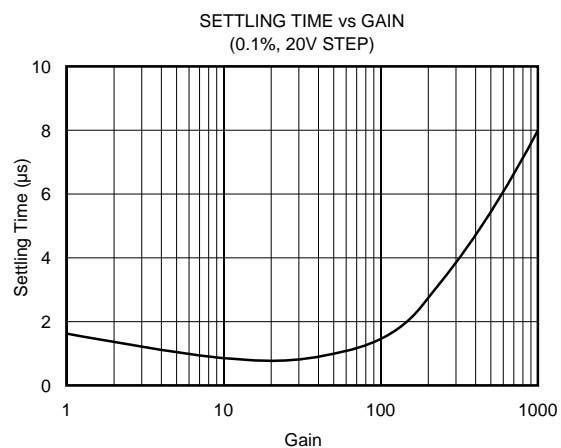
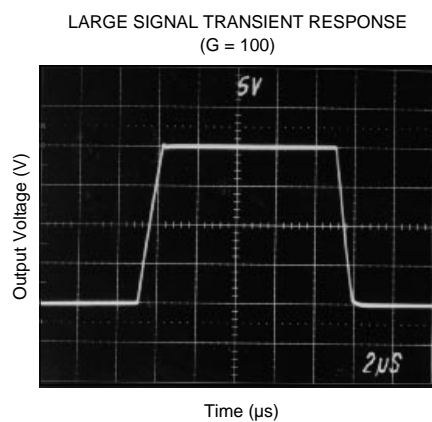
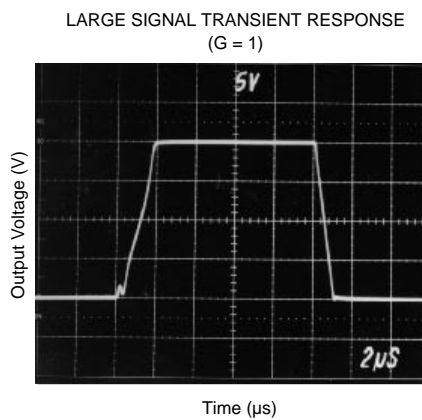
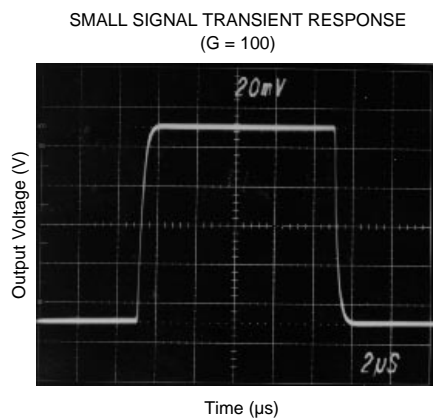
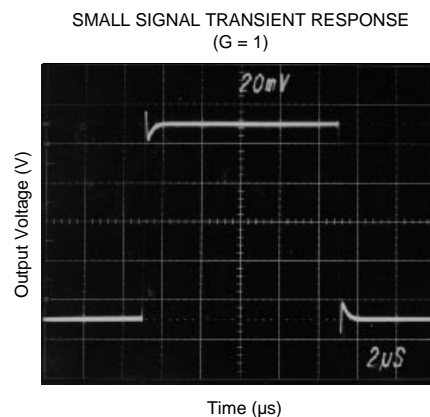
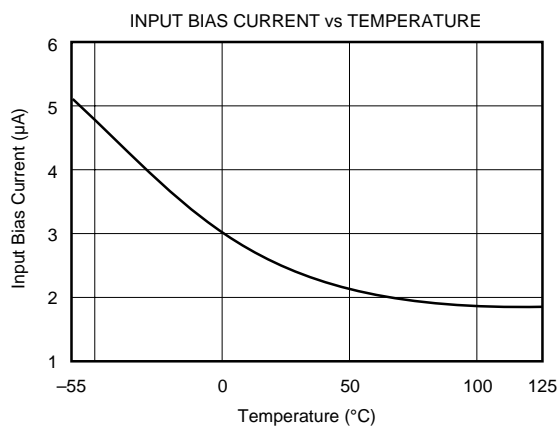
TYPICAL PERFORMANCE CURVES

At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$, unless otherwise noted.



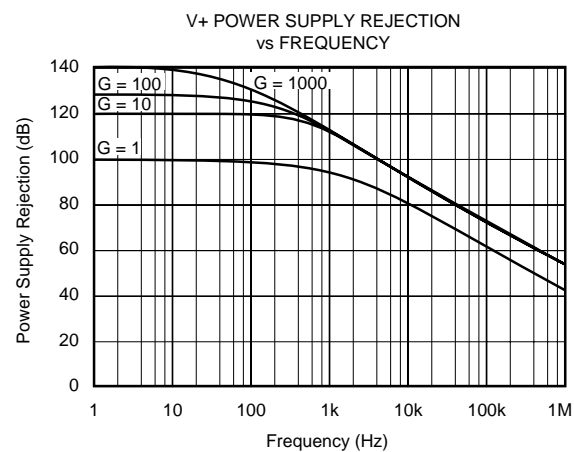
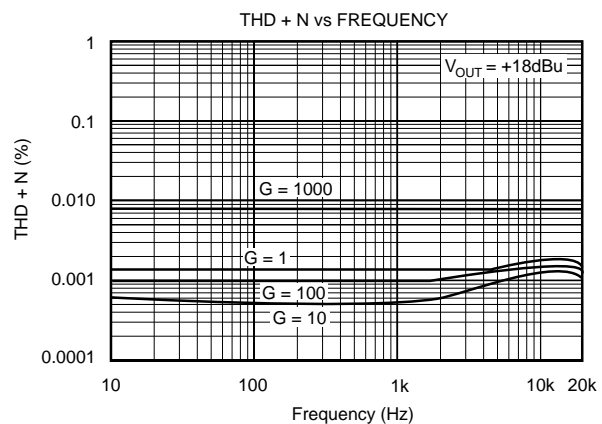
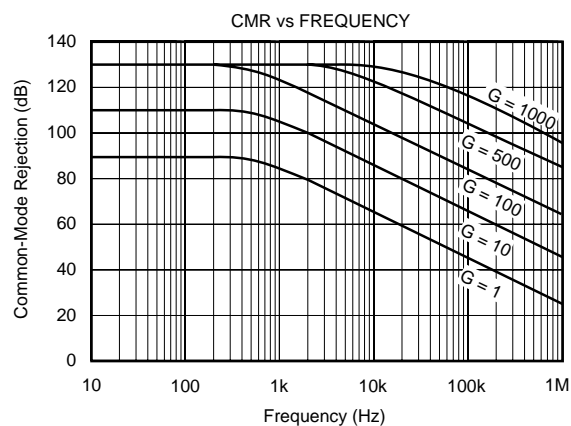
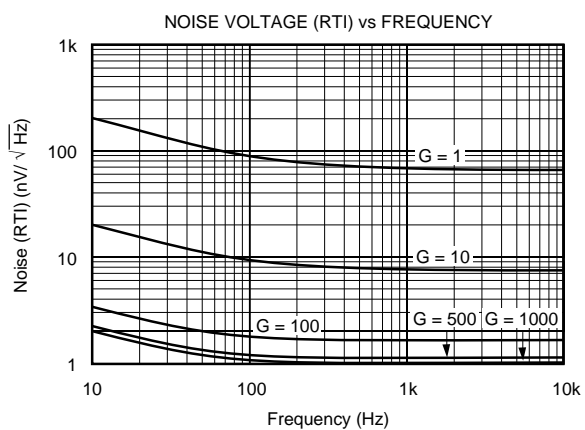
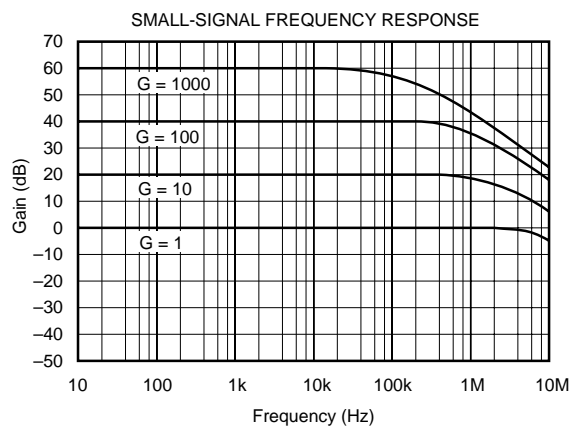
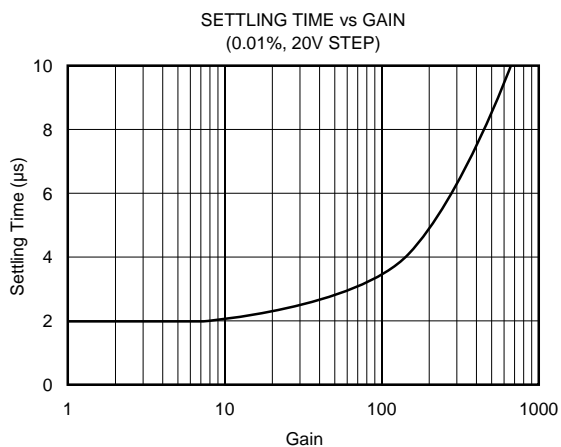
TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$, unless otherwise noted.



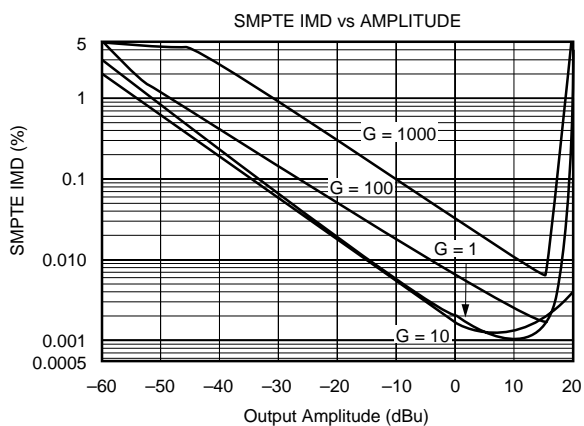
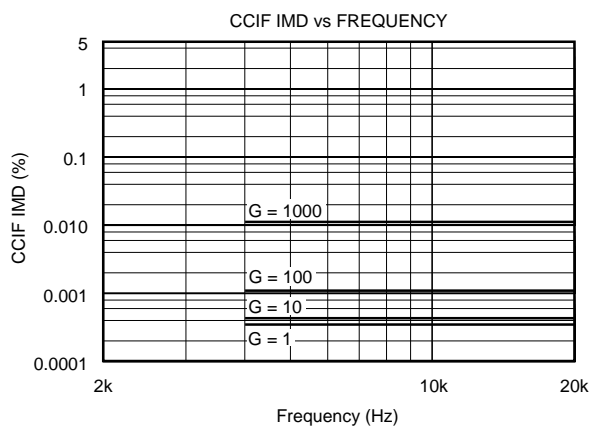
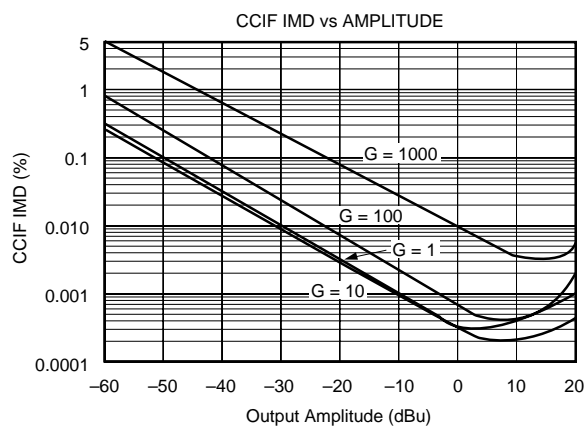
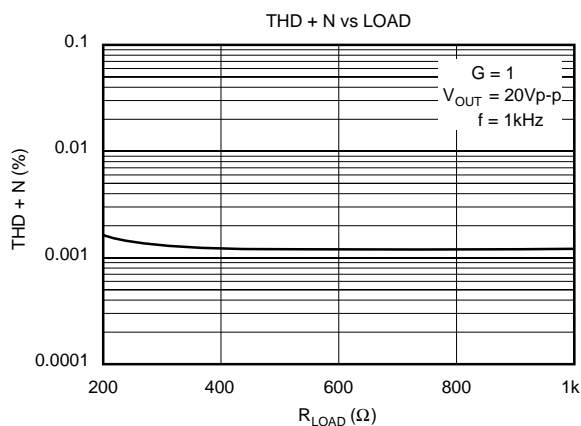
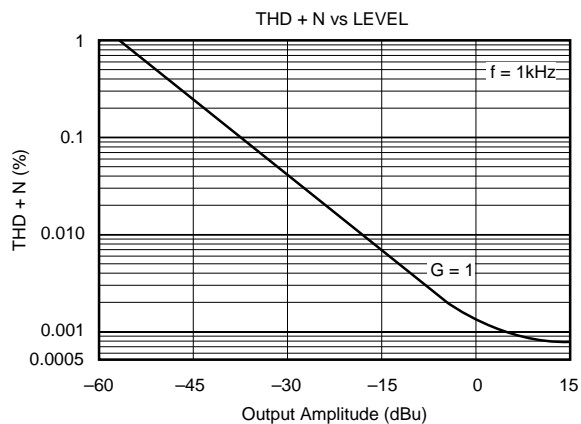
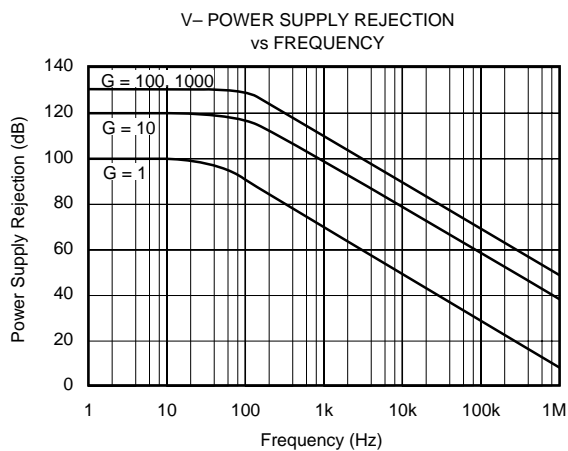
TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$, unless otherwise noted.



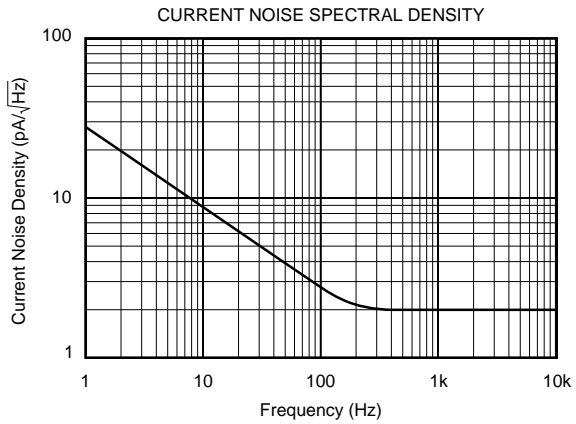
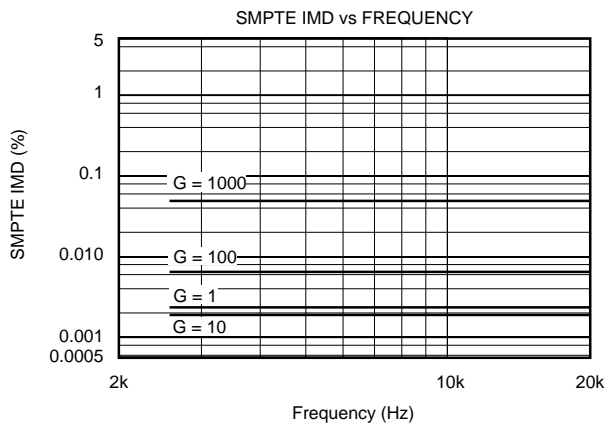
TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$, unless otherwise noted.



TYPICAL PERFORMANCE CURVES (CONT)

At $T_A = +25^\circ\text{C}$, $V_S = \pm 15\text{V}$ unless, otherwise noted.



APPLICATIONS INFORMATION

Figure 1 shows the basic connections required for operation. Power supplies should be bypassed with $1\mu\text{F}$ tantalum capacitors near the device pins. The output Sense (pin 11) and output Reference (pin 7) should be low impedance connections. Resistance of a few ohms in series with these connections will degrade the common-mode rejection of the amplifier.

To avoid oscillations, make short, direct connection to the gain set resistor and gain sense connections. Avoid running output signals near these sensitive input nodes.

INPUT CONSIDERATIONS

Certain source impedances can cause the INA103 to oscillate. This depends on circuit layout and source or cable characteristics connected to the input. An input network consisting of a small inductor and resistor (Figure 2) can greatly reduce the tendency to oscillate. This is especially

useful if various input sources are connected to the INA103. Although not shown in other figures, this network can be used, if needed, with all applications shown.

GAIN SELECTION

Gains of 1 or 100V/V can be set without external resistors. For $G = 1\text{V/V}$ (unity gain) leave pin 14 open (no connection)—see Figure 4. For $G = 100\text{V/V}$, connect pin 14 to pin 6—see Figure 5.

Gain can also be accurately set with a single external resistor as shown in Figure 1. The two internal feedback resistors are laser-trimmed to $3\text{k}\Omega$ within approximately $\pm 0.1\%$. The temperature coefficient of these resistors is approximately $50\text{ppm}/^\circ\text{C}$. Gain using an external R_G resistor is—

$$G = 1 + \frac{6\text{k}\Omega}{R_G}$$

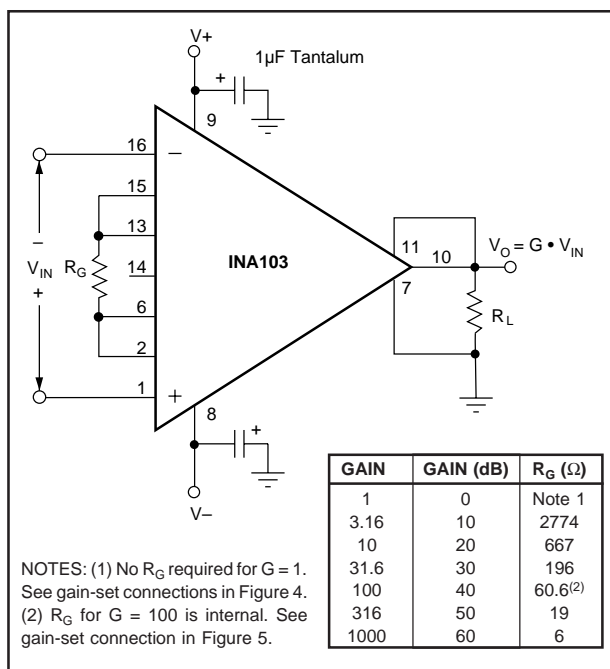


FIGURE 1. Basic Circuit Configuration.

Accuracy and TCR of the external R_G will also contribute to gain error and temperature drift. These effects can be directly inferred from the gain equation.

Connections available on A₁ and A₂ allow external resistors to be substituted for the internal 3kΩ feedback resistors. A precision resistor network can be used for very accurate and stable gains. To preserve the low noise of the INA103, the value of external feedback resistors should be kept low. Increasing the feedback resistors to 20kΩ would increase noise of the INA103 to approximately 1.5nV/√Hz. Due to the current-feedback input circuitry, bandwidth would also be reduced.

NOISE PERFORMANCE

The INA103 provides very low noise with low source impedance. Its 1nV/√Hz voltage noise delivers near theoretical noise performance with a source impedance of 200Ω. Relatively high input stage current is used to achieve this low noise. This results in relatively high input bias current and input current noise. As a result, the INA103 may not provide best noise performance with source impedances greater than 10kΩ. For source impedance greater than 10kΩ, consider the INA114 (excellent for precise DC applications), or the INA111 FET-input IA for high speed applications.

OFFSET ADJUSTMENT

Offset voltage of the INA103 has two components: input stage offset voltage is produced by A₁ and A₂; and, output stage offset is produced by A₃. Both input and output stage offset are laser trimmed and may not need adjustment in many applications.

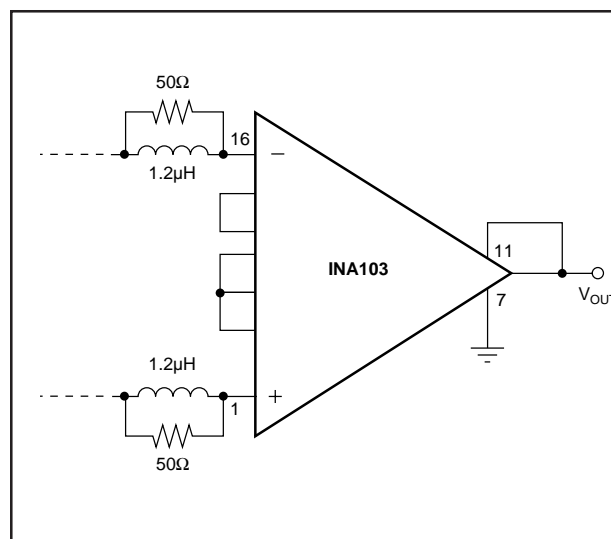


FIGURE 2. Input Stabilization Network.

Offset voltage can be trimmed with the optional circuit shown in Figure 3. This offset trim circuit primarily adjusts the output stage offset, but also has a small effect on input stage offset. For a 1mV adjustment of the output voltage, the input stage offset is adjusted approximately 1µV. Use this adjustment to null the INA103's offset voltage with zero differential input voltage. Do not use this adjustment to null offset produced by a sensor, or offset produced by subsequent stages, since this will increase temperature drift.

To offset the output voltage without affecting drift, use the circuit shown in Figure 4. The voltage applied to pin 7 is summed at the output. The op amp connected as a buffer provides a low impedance at pin 7 to assure good common-mode rejection.

Figure 5 shows a method to trim offset voltage in AC-coupled applications. A nearly constant and equal input bias current of approximately 2.5µA flows into both input terminals. A variable input trim voltage is created by adjusting the balance of the two input bias return resistances through which the input bias currents must flow.

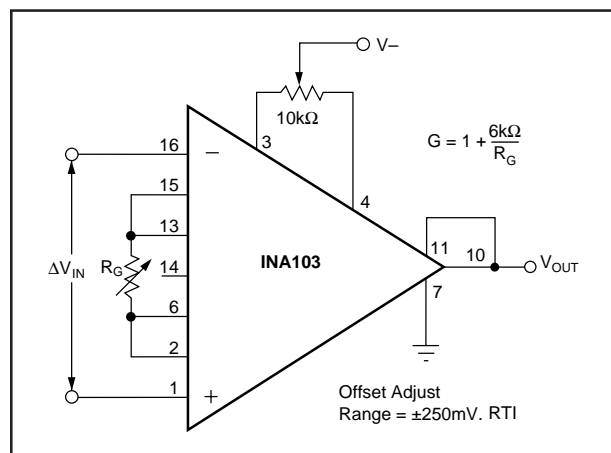


FIGURE 3. Offset Adjustment Circuit.

Figure 6 shows an active control loop that adjusts the output offset voltage to zero. A_2 , R , and C form an integrator that produces an offsetting voltage applied to one input of the INA103. This produces a -6dB/octave low frequency roll-off like the capacitor input coupling in Figure 5.

COMMON-MODE INPUT RANGE

For proper operation, the combined differential input signal and common-mode input voltage must not cause the input amplifiers to exceed their output swing limits. The linear input range is shown in the typical performance curve “Maximum Common-Mode Voltage vs Output Voltage.” For a given total gain, the input common-mode range can be increased by reducing the input stage gain and increasing the output stage gain with the circuit shown in Figure 7.

OUTPUT SENSE

An output sense terminal allows greater gain accuracy in driving the load. By connecting the sense connection at the load, $I \cdot R$ voltage loss to the load is included inside the feedback loop. Current drive can be increased by connecting a current booster inside the feedback loop as shown in Figure 11.

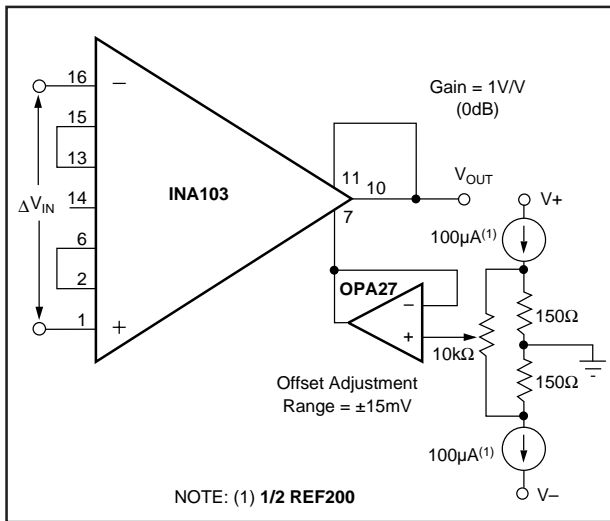


FIGURE 4. Output Offsetting.

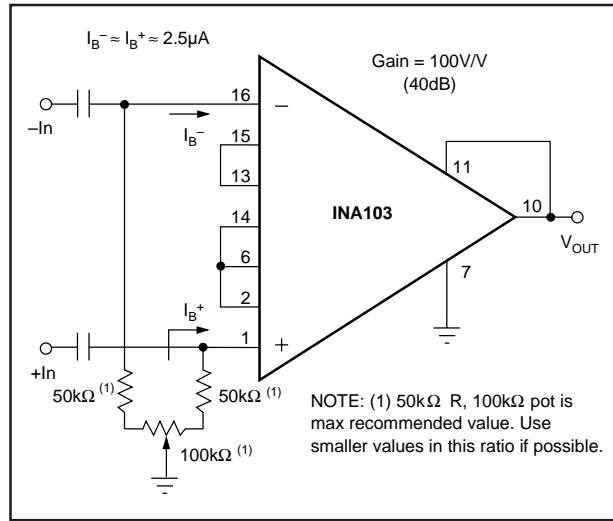


FIGURE 5. Input Offset Adjustment for AC-Coupled Inputs.

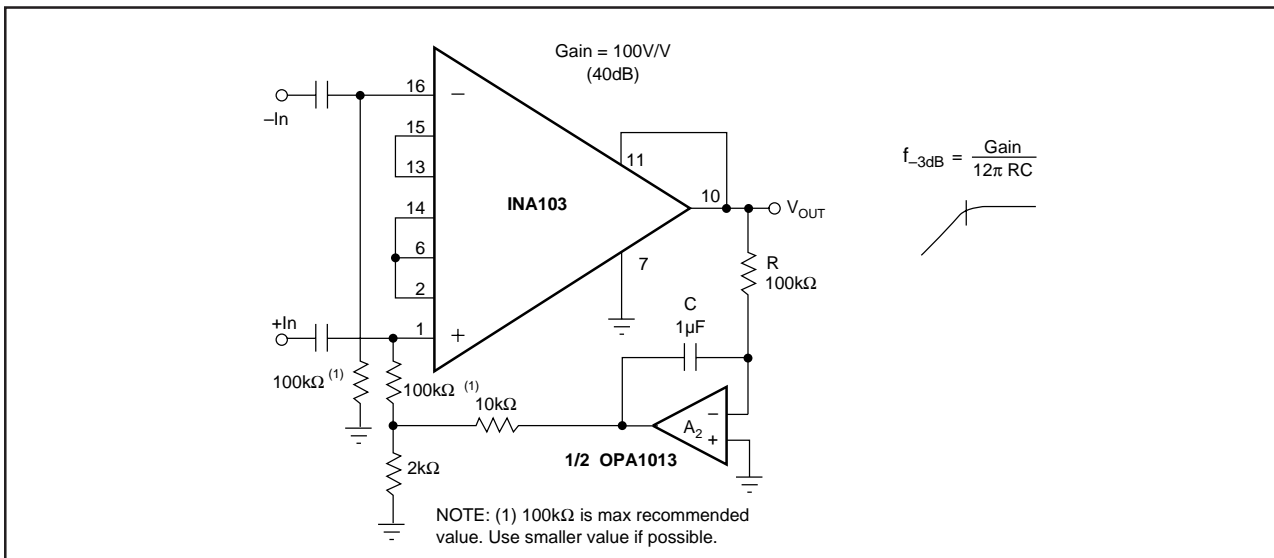


FIGURE 6. Automatic DC Restoration.

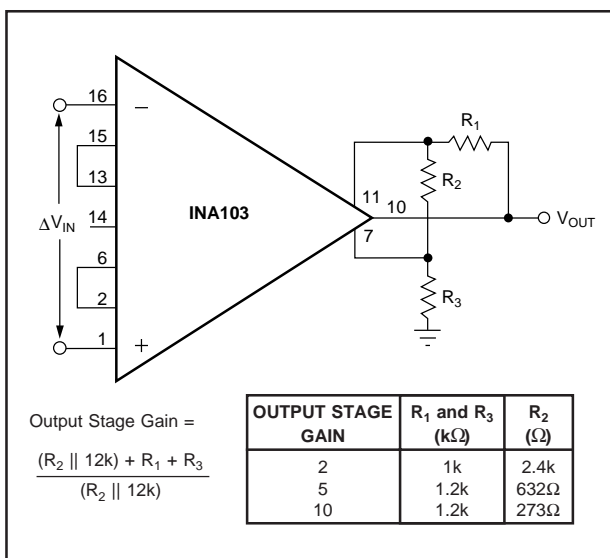


FIGURE 7. Gain Adjustment of Output Stage.

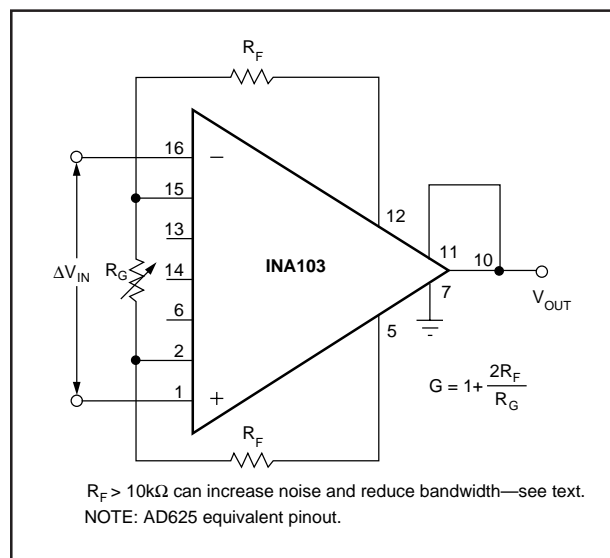


FIGURE 8. Use of External Resistors for Gain Set.

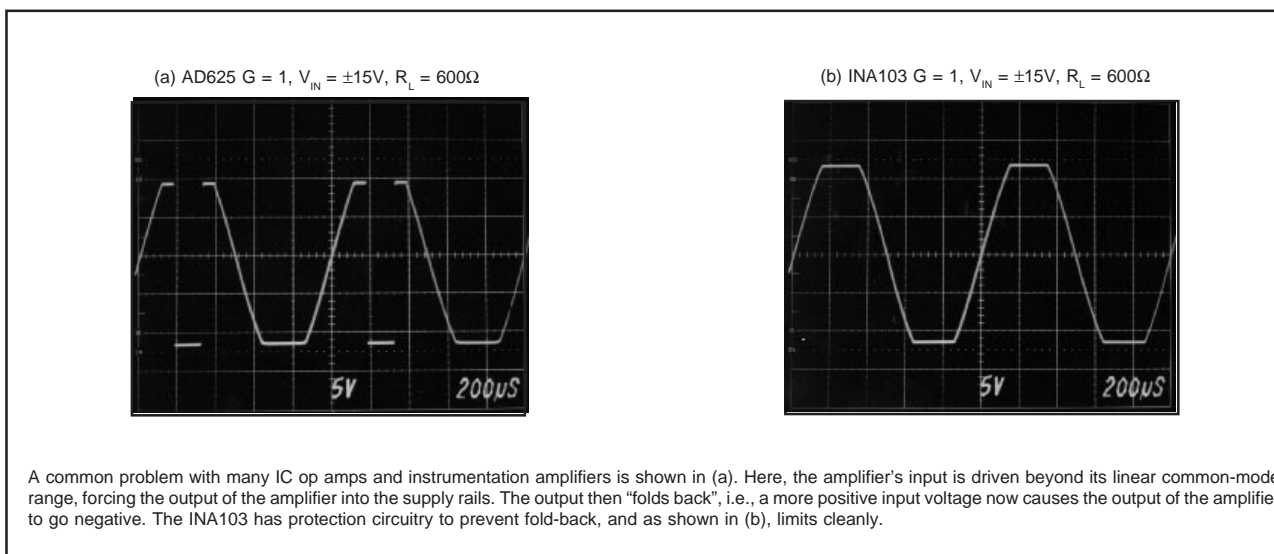


FIGURE 9. INA103 Overload Condition Performance.

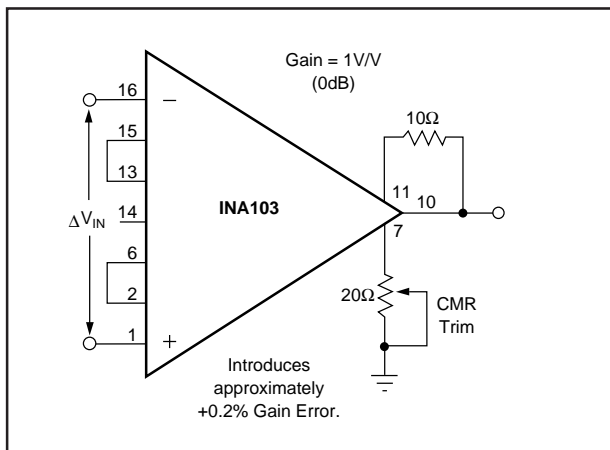


FIGURE 10. Optional Circuit for Externally Trimming CMR.

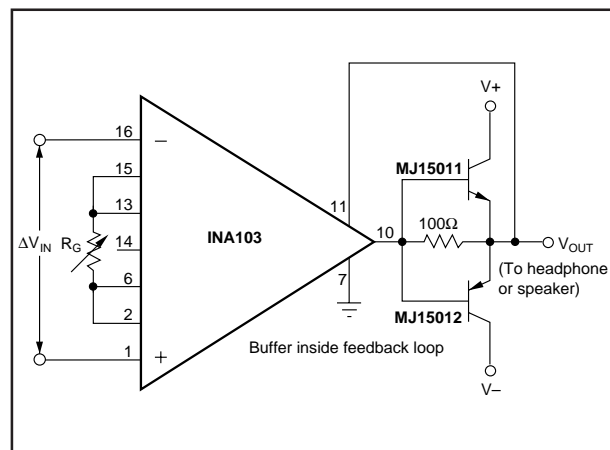


FIGURE 11. Increasing Output Circuit Drive.

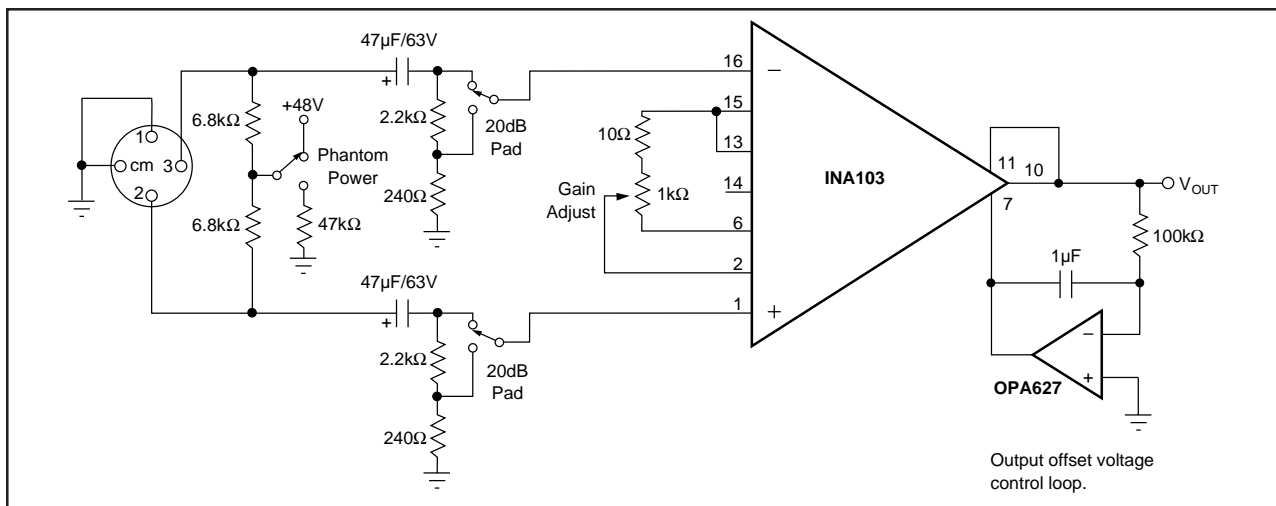


FIGURE 12. Microphone Preamplifier with Provision for Phantom Power Microphones.

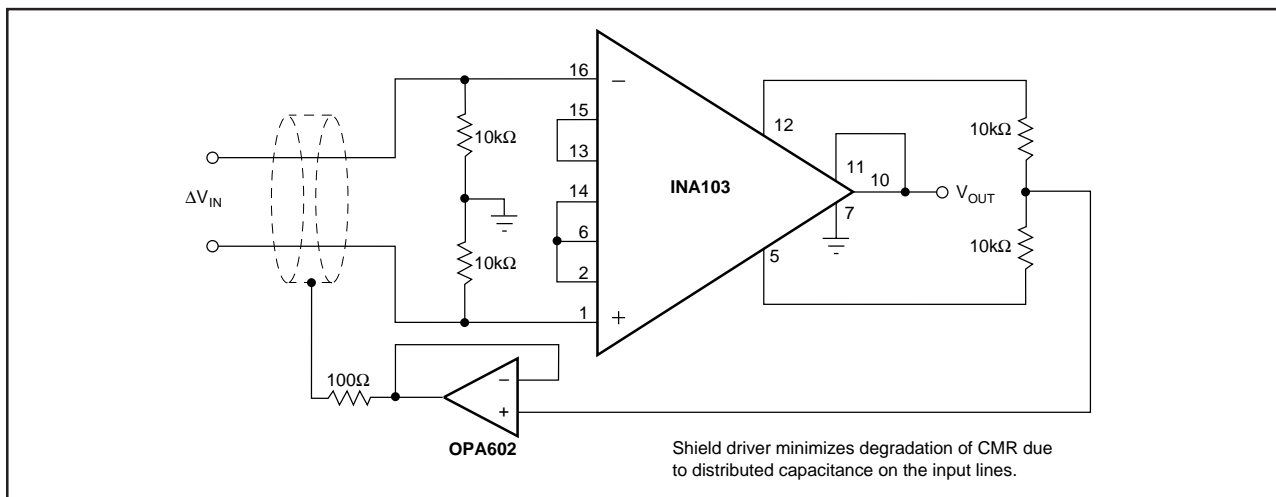


FIGURE 13. Instrumentation Amplifier with Shield Driver.

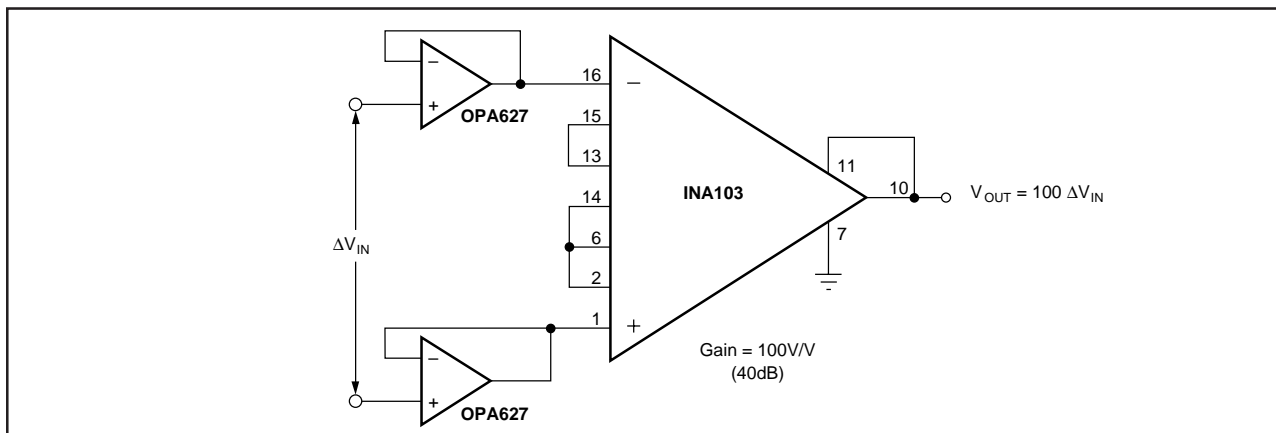


FIGURE 14. Gain-of-100 INA103 with FET Buffers.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
INA103KP	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	INA103KP	Samples
INA103KPG4	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	CU NIPDAU	N / A for Pkg Type	-40 to 85	INA103KP	Samples
INA103KU	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU-DCC	Level-3-260C-168 HR		INA103KU	Samples
INA103KU/1K	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU-DCC	Level-3-260C-168 HR		INA103KU	Samples
INA103KU/1KE4	ACTIVE	SOIC	DW	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU-DCC	Level-3-260C-168 HR		INA103KU	Samples
INA103KUG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU-DCC	Level-3-260C-168 HR		INA103KU	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

⁽⁶⁾ Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
INA103KU/1K	SOIC	DW	16	1000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

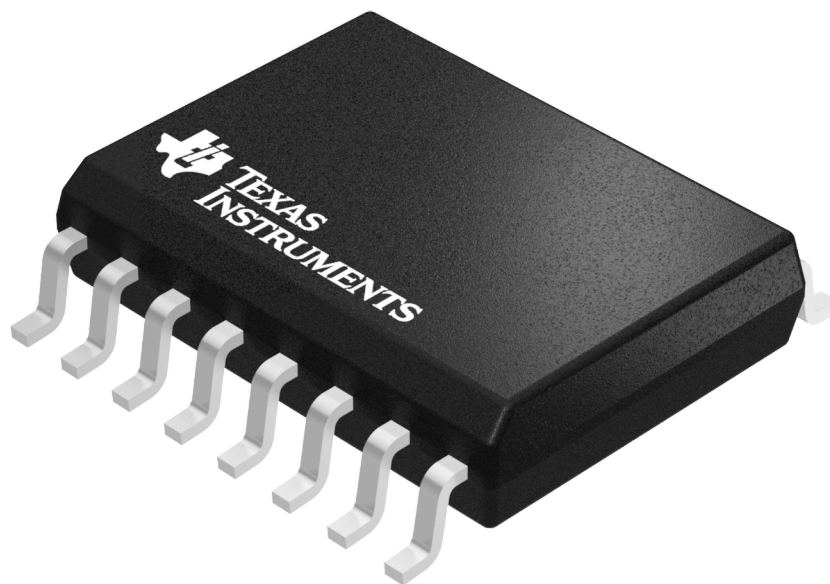
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
INA103KU/1K	SOIC	DW	16	1000	367.0	367.0	38.0

DW 16

GENERIC PACKAGE VIEW

SOIC - 2.65 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



Images above are just a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

4040000-2/H



DW0016A

PACKAGE OUTLINE

SOIC - 2.65 mm max height

SOIC



4220721/A 07/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

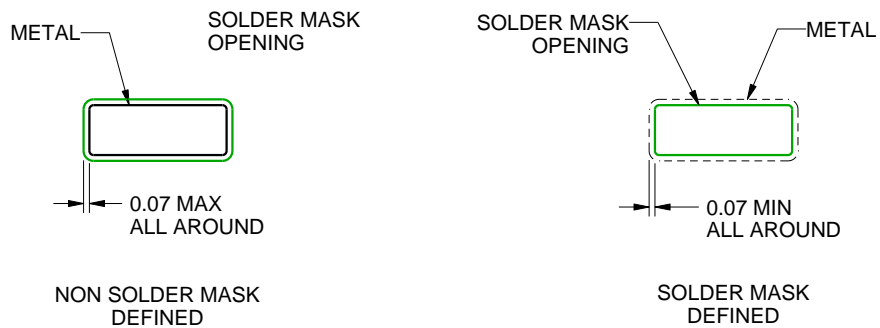
DW0016A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:7X



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0016A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

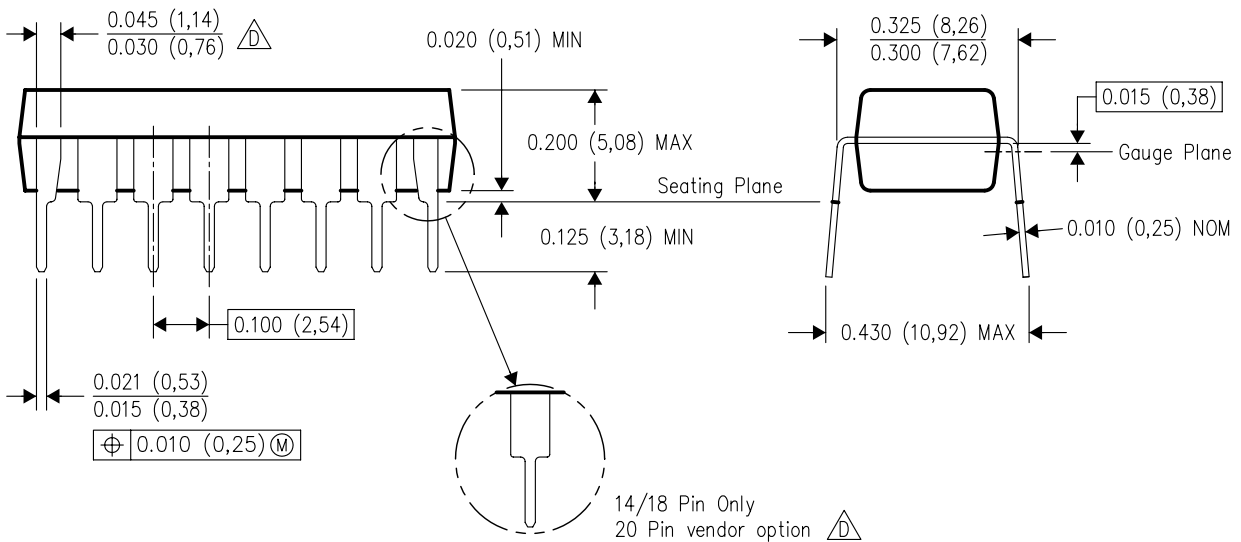
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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